Vincotech

10-FZ12PNA015M7-P840C28
datasheet

flow PIM 0 **1200 V / 15 A**

Features

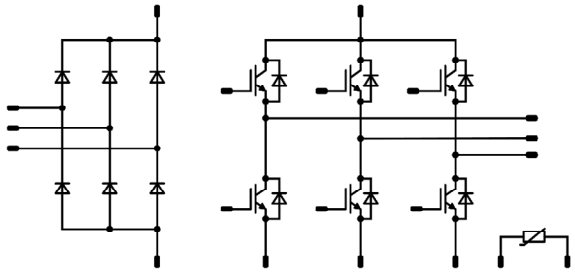
- IGBT M7 with low V_{CEsat} and improved EMC behavior
- Open emitter configuration
- Compact and low inductive design
- Builtin NTC

flow 0 12 mm housing

Target applications

- Industrial Drives

Schematic



Types

- 10-FZ12PNA015M7-P840C28

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Rectifier Diode				
Peak Repetitive Reverse Voltage	V_{RRM}		1600	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ T_s = 80 °C	25	A
Surge (non-repetitive) forward current	I_{FSM}	50 Hz Single Half Sine Wave t_p = 10 ms T_j = 150 °C	200	A
Surge current capability	I^2t		200	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	44	W
Maximum Junction Temperature	T_{jmax}		150	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ T_s = 80 °C	15	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	60	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ T_s = 80 °C	15	A
Repetitive peak forward current	I_{FRM}		30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	45	W
Maximum junction temperature	T_{jmax}		175	°C
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	6000	V
		AC Voltage t_p = 1 min	2500	V
Creepage distance			min. 12,7	mm
Clearance			9,29	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Rectifier Diode										
Static										
Forward voltage	V_F				25	25 125		1,22 1,21	1,8	V
Reverse leakage current	I_r			1600		25 145			50 1100	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,59		K/W
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,0015	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150		1,70 1,95 2,01	2,15	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			60	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		2900		pF
Output capacitance	C_{oes}							120		
Reverse transfer capacitance	C_{res}							34		
Gate charge	Q_g		15	600	15	25		110		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,60		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{goff} = 32 Ω R_{gon} = 32 Ω	±15	600	15	25 150		176 174		ns
Rise time	t_r					25 150		43 48		
Turn-off delay time	$t_{d(off)}$					25 150		191 218		
Fall time	t_f					25 150		119 127		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 1,5 µC Q_{rFWD} = 2,6 µC				25 150		1,548 2,008		mWs
Turn-off energy (per pulse)	E_{off}					25 150		0,925 1,322		

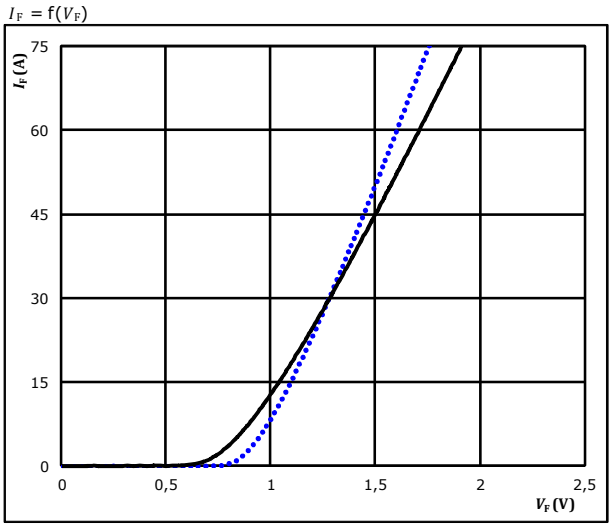
Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				15	25 125		1,63 1,74	2,1	V
Reverse leakage current	I_R			1200		25			30	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,11		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 293 A/µs di/dt = 244 A/µs	±15	600	15	25 150		11 12		A
Reverse recovery time	t_{rr}					25 150		265 423		ns
Recovered charge	Q_r					25 150		1,549 2,592		µC
Reverse recovered energy	E_{rec}					25 150		0,488 0,938		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 150		92 52		A/µs
Thermistor										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1484 Ω				100	-5		5	%
Power dissipation	P					25		5		mW
Power dissipation constant						25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %				25		3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %				25		4000		K
Vincotech NTC Reference									I	

Rectifier Diode Characteristics

figure 1. **FWD**

Typical forward characteristics



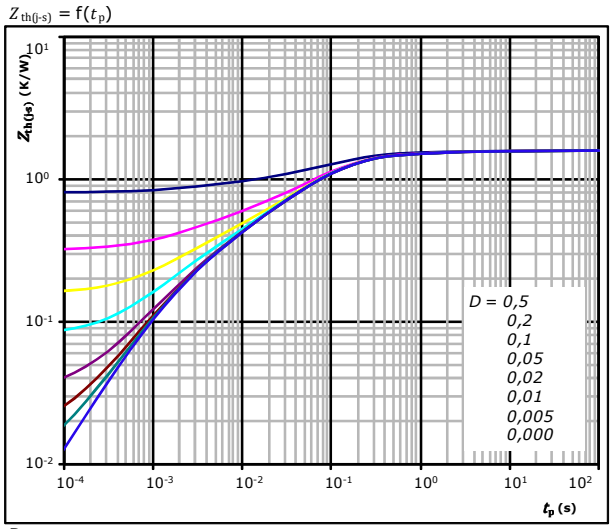
t_p = 250 µs

T_j: 25 °C

T_j: 125 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width



D = t_p / T

$R_{th(j-s)}$ = 1,59 K/W

Diode thermal model values

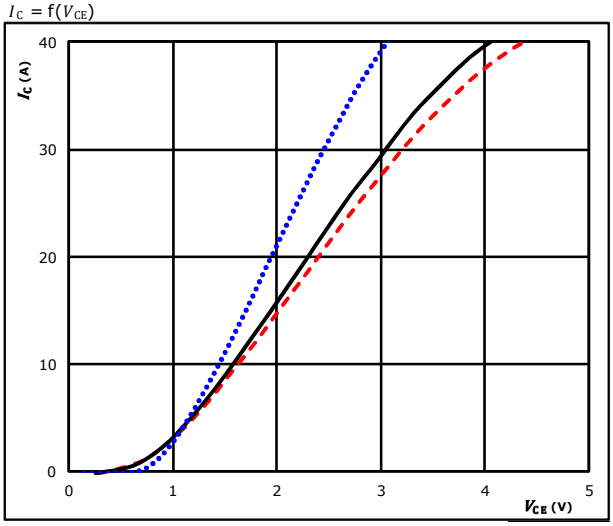
R (K/W)	τ (s)
3,44E-02	9,66E+00
1,12E-01	1,22E+00
5,81E-01	1,45E-01
4,89E-01	5,05E-02
2,38E-01	9,26E-03
1,22E-01	1,79E-03
1,22E-01	1,79E-03

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

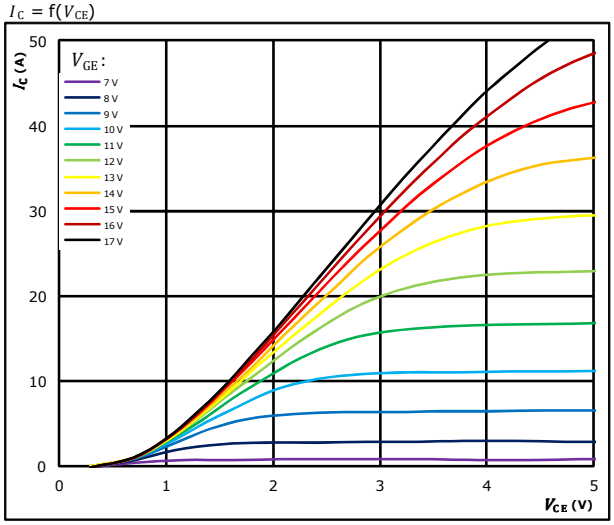


t_p =	250	µs		25 °C	
V_{GE} =	15	V	T_j:	125 °C	
				150 °C	

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

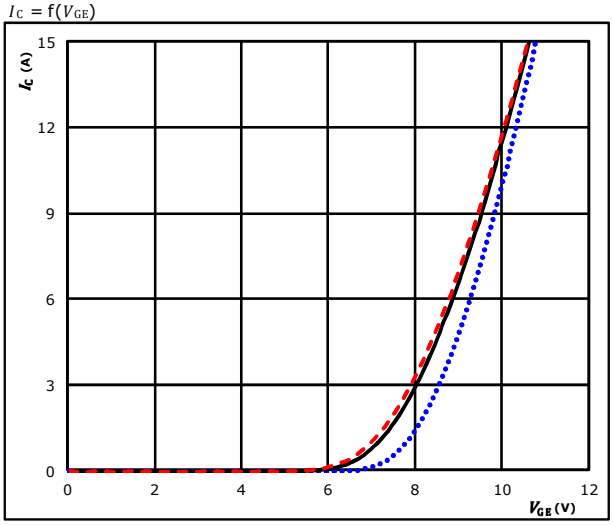


t_p =	250	µs	
T_j =	150	°C	
V_{GE} from	7 V to 17 V in steps of 1 V		

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

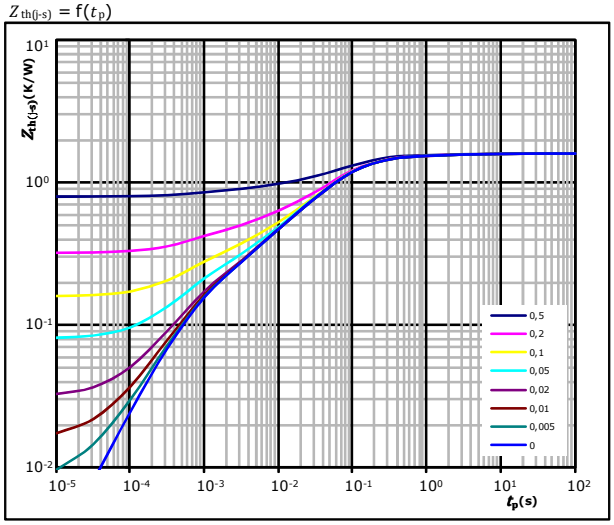


t_p =	100	µs		25 °C	
V_{CE} =	10	V	T_j:	125 °C	
				150 °C	

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	1,60	K/W

IGBT thermal model values

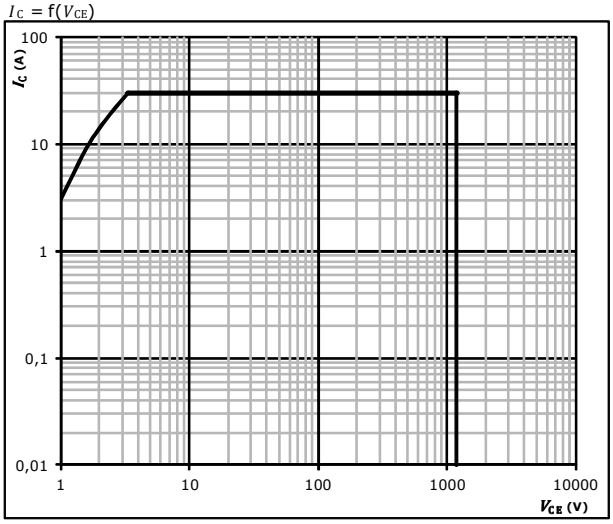
R (K/W)	τ (s)
4,90E-02	4,40E+00
1,40E-01	5,34E-01
8,04E-01	8,02E-02
2,98E-01	2,57E-02
1,69E-01	5,09E-03
1,35E-01	6,41E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



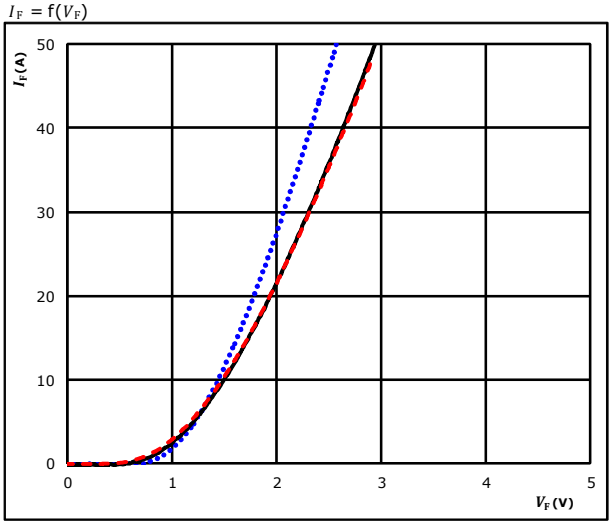
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



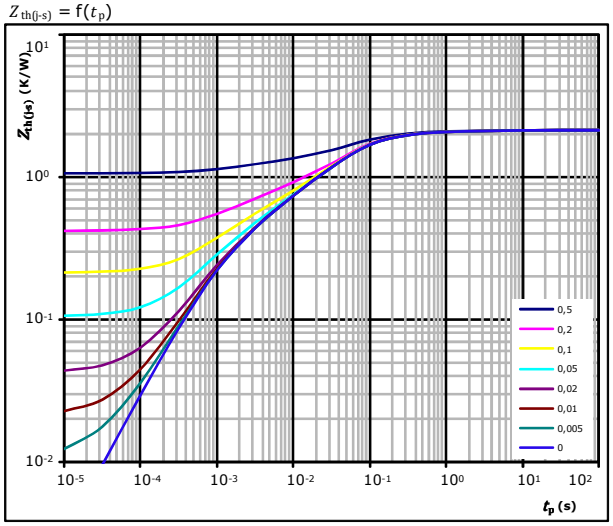
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 2,11 K/W

FWD thermal model values

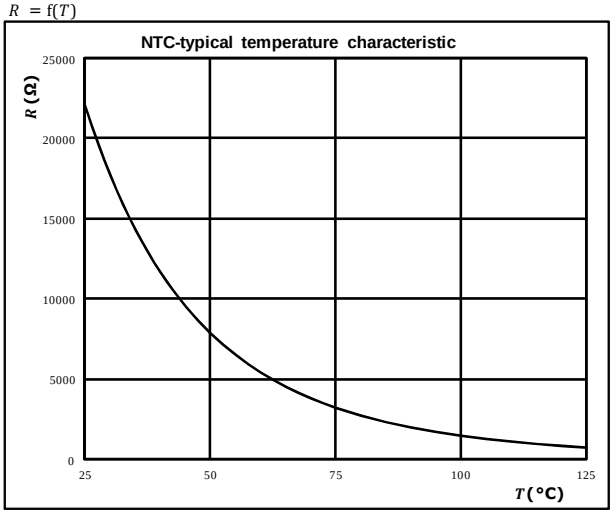
R (K/W)	τ (s)
8,99E-02	2,33E+00
4,04E-01	1,91E-01
1,05E+00	4,49E-02
3,39E-01	6,08E-03
2,29E-01	1,02E-03

Thermistor Characteristics

figure 1. **Thermistor**

Typical NTC characteristic
as a function of temperature

$R = f(T)$

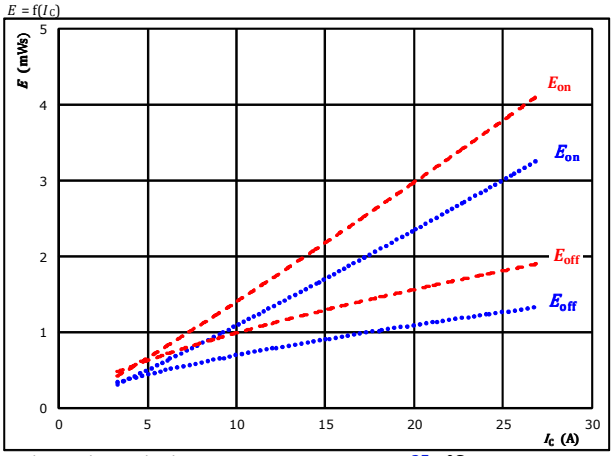


Inverter Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



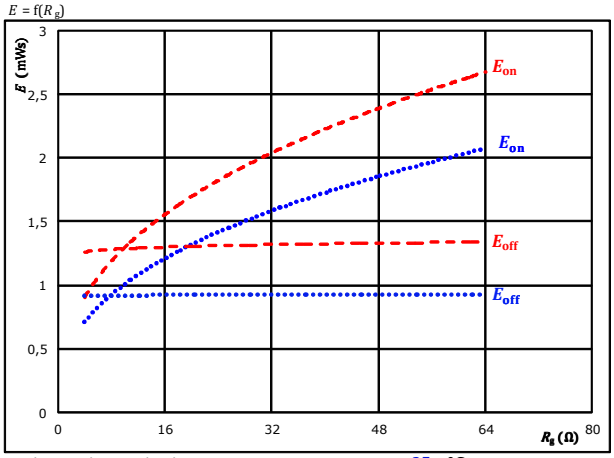
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	•••••••••••••
V_{GE} =	±15	V		150 °C	— — — —
R_{gon} =	32	Ω			
R_{goff} =	32	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



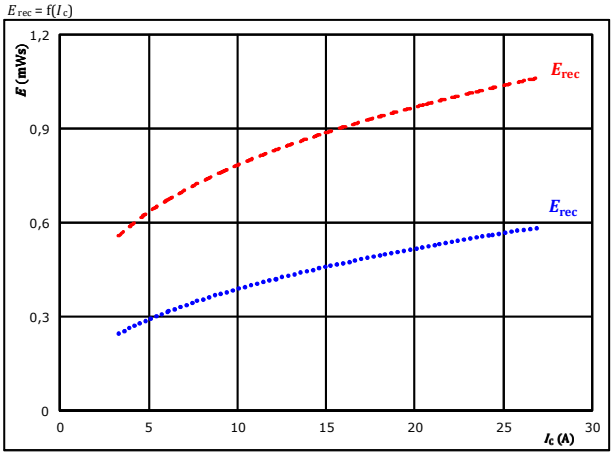
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	•••••••••••••
V_{GE} =	±15	V		150 °C	— — — —
I_C =	15	A			

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



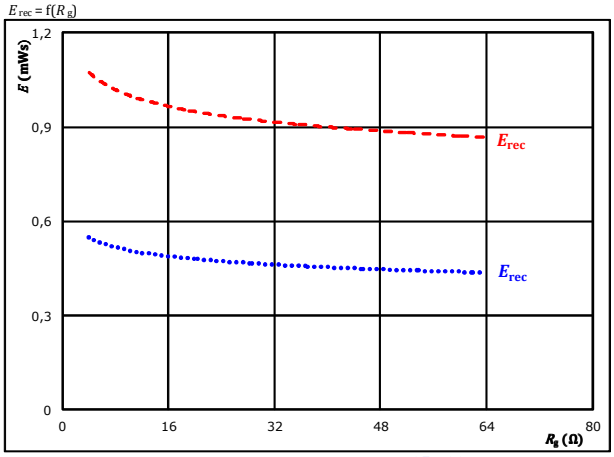
With an inductive load at

V_{CE} =	600	V	T_J:	25 °C	•••••••••••••
V_{GE} =	±15	V		150 °C	— — — —
R_{gon} =	32	Ω			

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

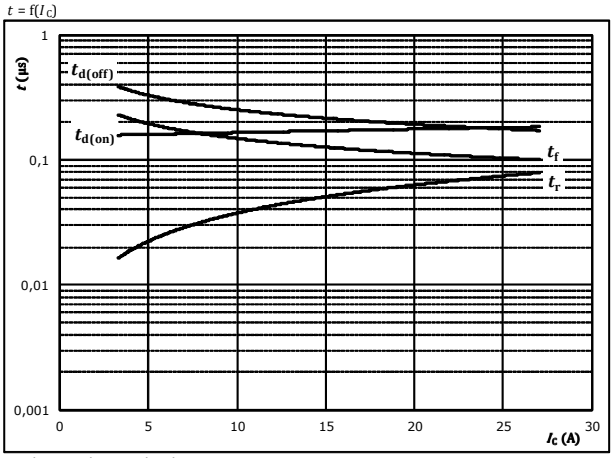
V_{CE} =	600	V	T_J:	25 °C	•••••••••••••
V_{GE} =	±15	V		150 °C	— — — —
I_C =	15	A			

Inverter Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



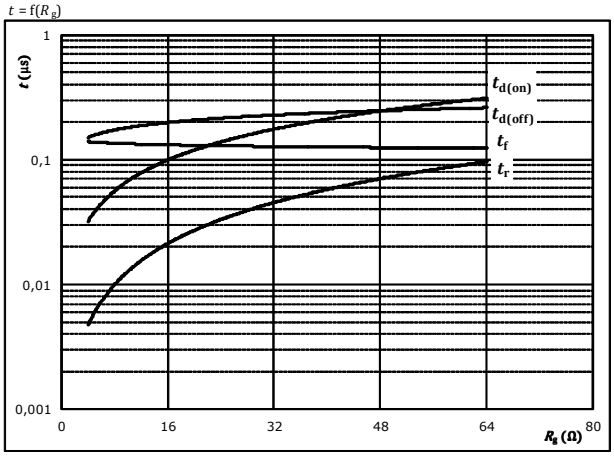
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



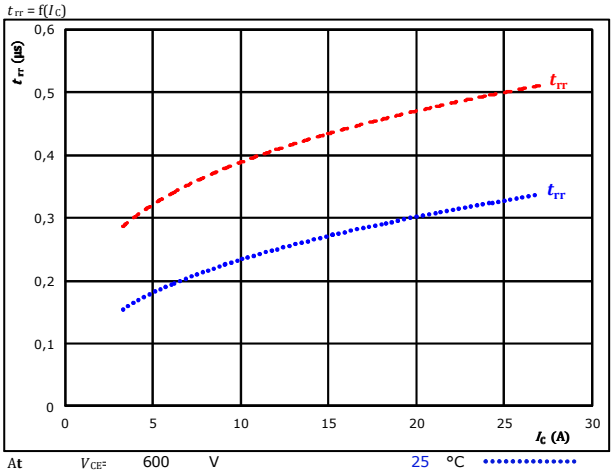
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

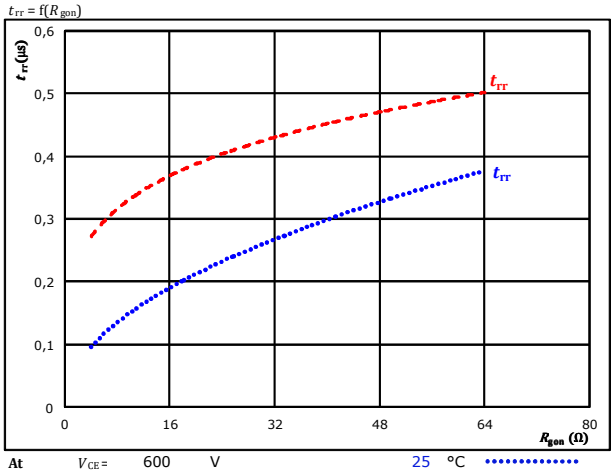


At					
V_{CE} =	600	V		25 °C	·····
V_{GE} =	±15	V	T_j:	150 °C	– – –
R_{gon} =	32	Ω			

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



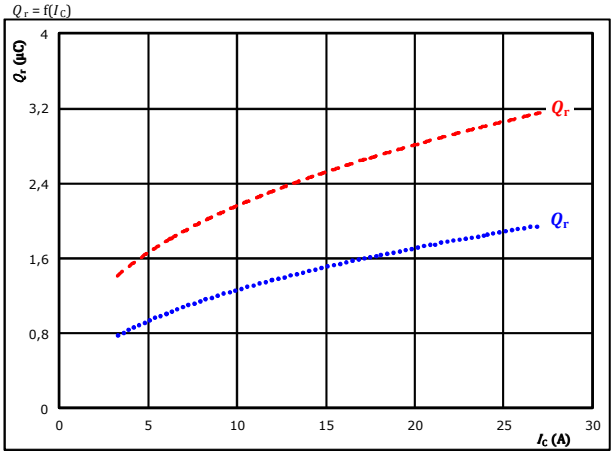
At					
V_{CE} =	600	V		25 °C	·····
V_{GE} =	±15	V	T_j:	150 °C	– – –
I_C =	15	A			

Inverter Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

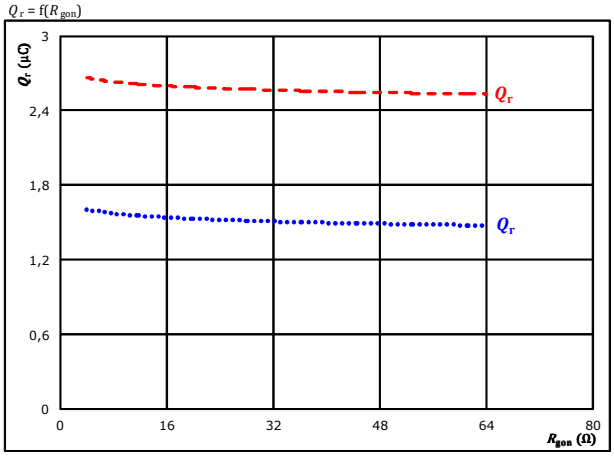


At						
	V_{CE} =	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	150 °C	
	R_{gon} =	32	Ω			

figure 10. **FWD**

Typical recoved charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

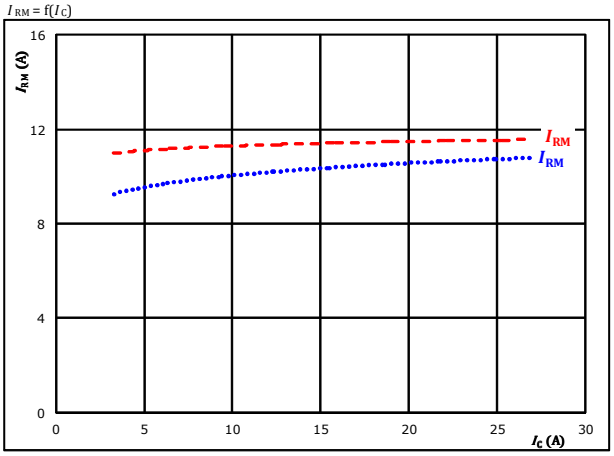


At						
	V_{CE}=	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	150 °C	
	I_C=	15	A			

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

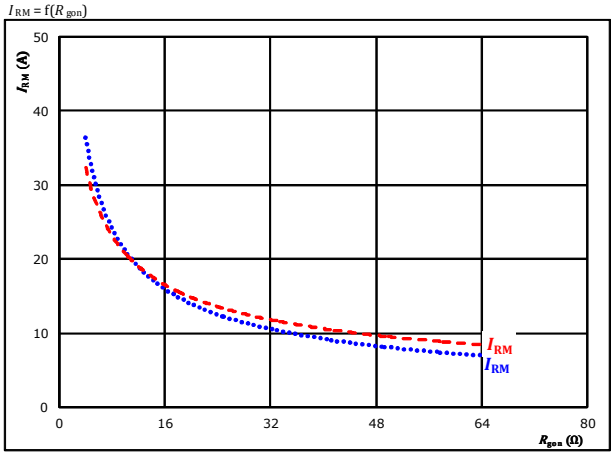


At						
	V_{CE}:	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	150 °C	
	R_{gon} =	32	Ω			

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



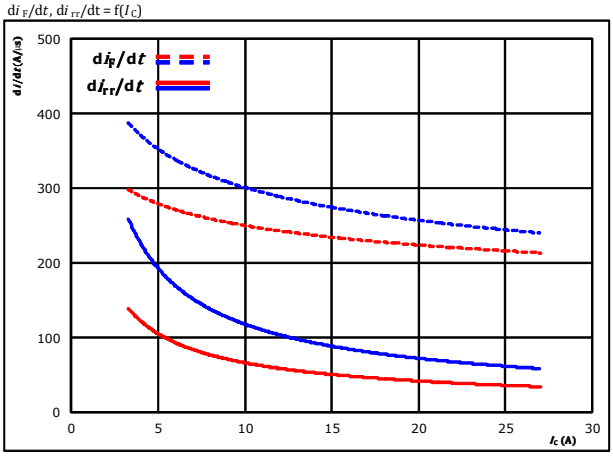
At						
	V_{CE} =	600	V		25 °C	
	V_{GE} =	±15	V	T_j:	150 °C	
	I_C =	15	A			

Inverter Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_F/dt, di_{rr}/dt = f(I_C)$

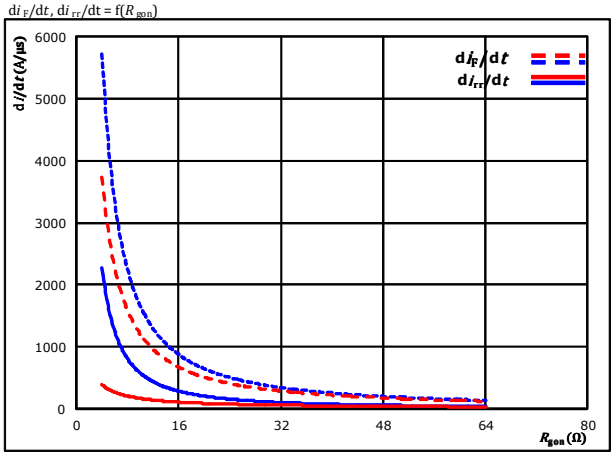


At						
V_{CE}:	600	V		25	°C	•••••••••••••
V_{GE} =	±15	V	T_j:	150	°C	— — —
R_{gon} =	32	Ω				

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$di_F/dt, di_{rr}/dt = f(R_{gon})$

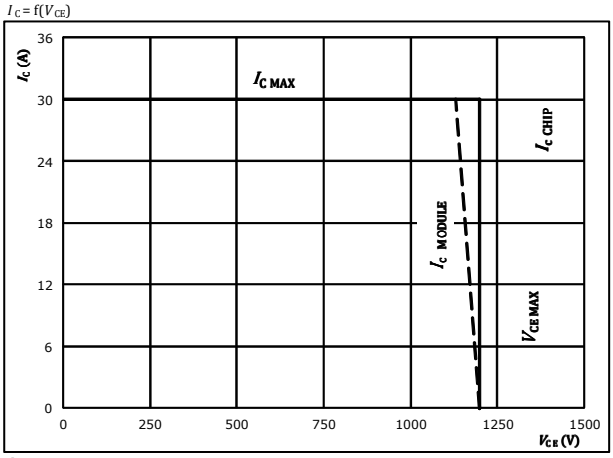


At						
V_{CE} =	600	V		25	°C	•••••••••••••
V_{GE} =	±15	V	T_j:	150	°C	— — —
I_C=	15	A				

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

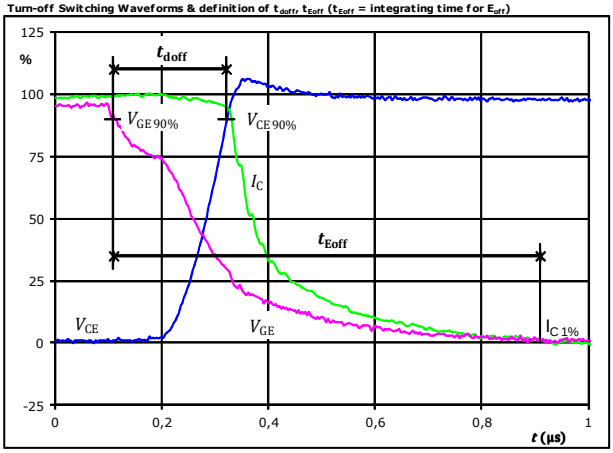
T_j =	175	°C
R_{gon} =	32	Ω
R_{goff} =	32	Ω

Inverter Switching Definitions

General conditions		
T_j	=	150 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. IGBT

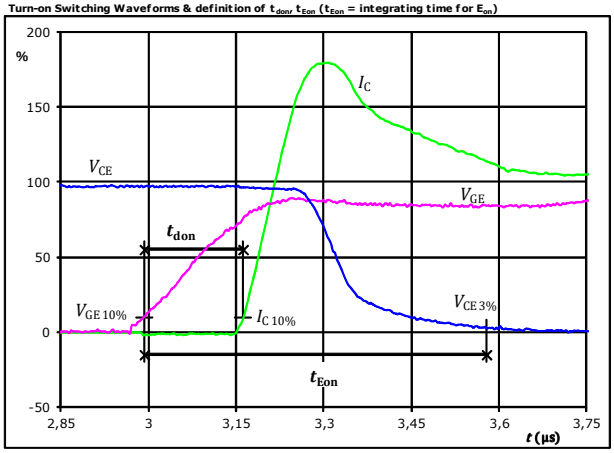
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{doff} =	0,218	µs
t_{Eoff} =	0,800	µs

figure 2. IGBT

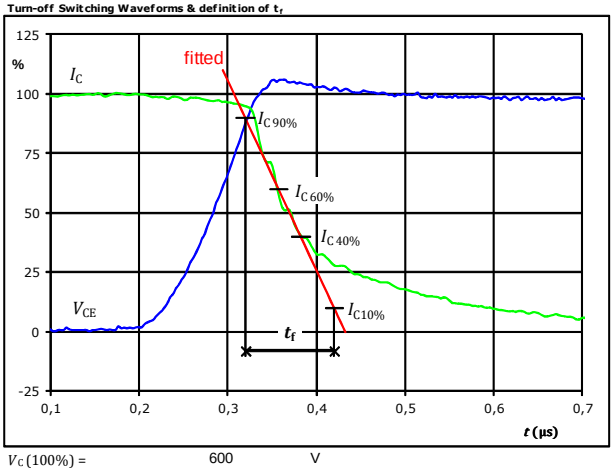
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{don} =	0,174	µs
t_{Eon} =	0,586	µs

figure 3. IGBT

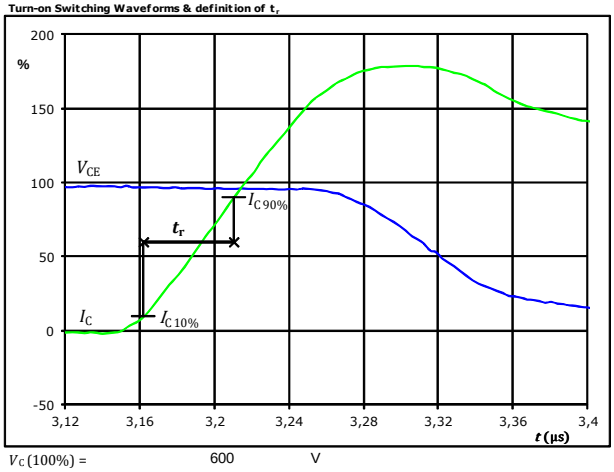
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_f =	0,127	µs

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

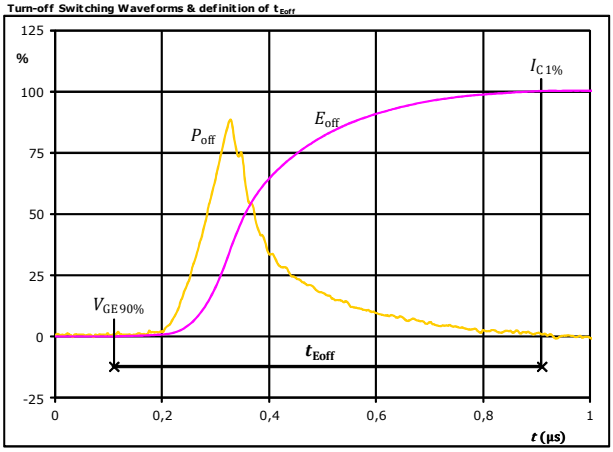


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_r =	0,048	µs

Inverter Switching Characteristics

figure 5. **IGBT**

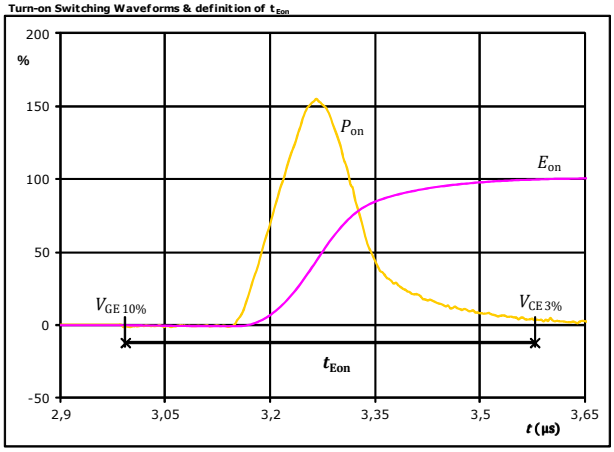
Turn-off Switching Waveforms & definition of t_{Eoff}



$P_{off}(100\%)$ =	9,24	kW
$E_{off}(100\%)$ =	1,32	mJ
t_{Eoff} =	0,80	µs

figure 6. **IGBT**

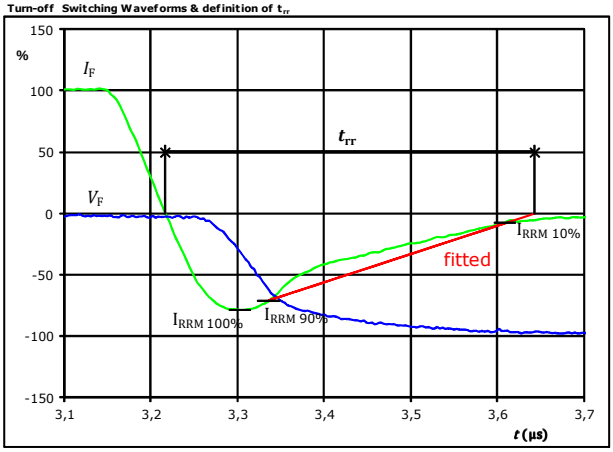
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on}(100\%)$ =	9,24	kW
$E_{on}(100\%)$ =	2,01	mJ
t_{Eon} =	0,59	µs

figure 7. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

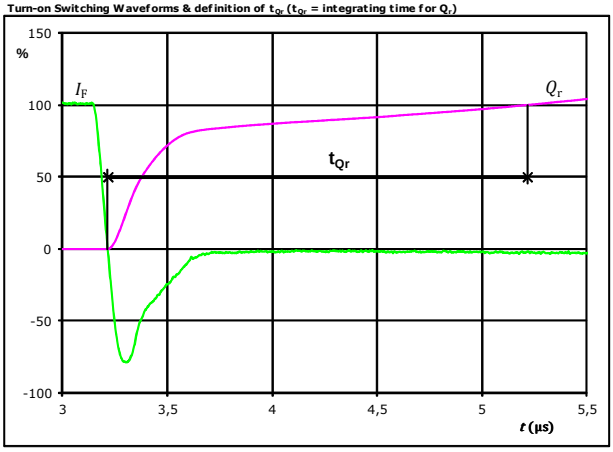


$V_F(100\%)$ =	600	V
$I_F(100\%)$ =	15	A
$I_{RRM}(100\%)$ =	-12	A
t_{rr} =	0,423	µs

Inverter Switching Characteristics

figure 8. **FWD**

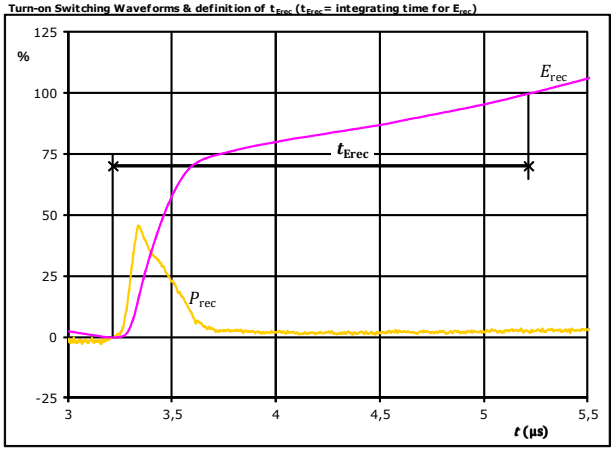
Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	15	A
Q_r (100%) =	2,59	µC
t_{Qr} =	2,00	µs

figure 9. **FWD**

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec} = integrating time for E_{rec})



P_{rec} (100%) =	9,24	kW
E_{rec} (100%) =	0,94	mJ
t_{Erec} =	2,00	µs

Vincotech

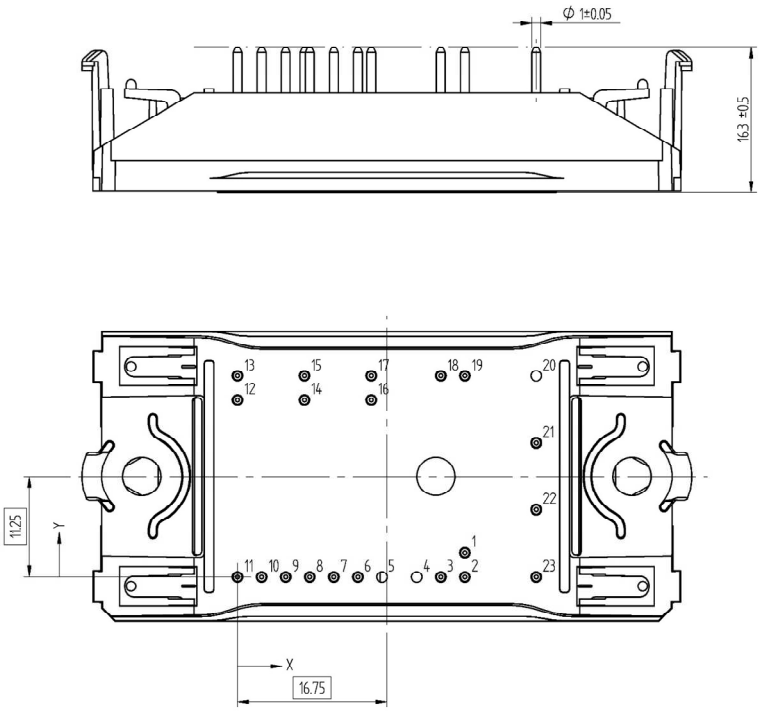
Ordering Code & Marking

Version	Ordering Code
without thermal paste 12 mm housing with solder pins	10-FZ12PNA015M7-P840C28
with thermal paste 12 mm housing with solder pins	10-FZ12PNA015M7-P840C28-/3/

		Name		Date code	UL & VIN	Lot	Serial
Text		NN-NNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
		Type&Ver	**Lot number**	**Serial**	**Date code**		
Datamatrix		TTTTTTTVV	LLLLL	SSSS	WWYY		

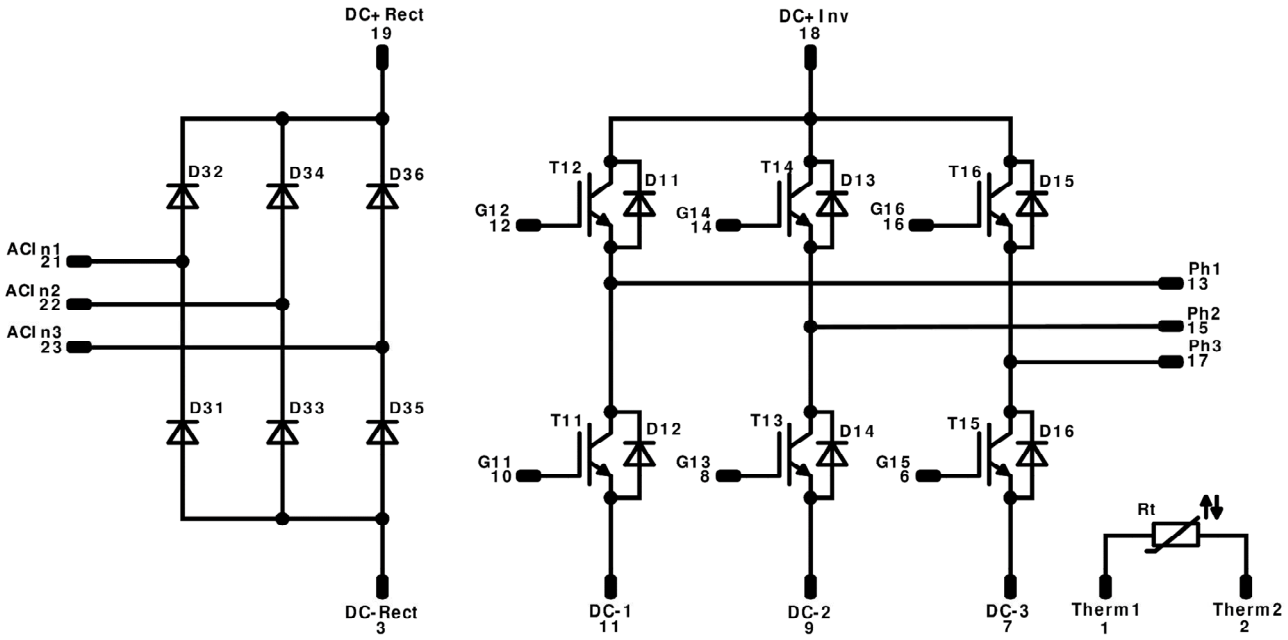
Outline

Pin table			
Pin	X	Y	Function
1	25,5	2,7	Therm1
2	25,5	0	Therm2
3	22,8	0	DC-Rect
4	Not assembled		
5	Not assembled		
6	13,5	0	G15
7	10,8	0	DC-3
8	8,1	0	G13
9	5,4	0	DC-2
10	2,7	0	G11
11	0	0	DC-1
12	0	19,8	G12
13	0	22,5	Ph1
14	7,5	19,8	G14
15	7,5	22,5	Ph2
16	15	19,8	G16
17	15	22,5	Ph3
18	22,8	22,5	DC+Inv
19	25,5	22,5	DC+Rect
20	Not assembled		
21	33,5	15	ACIn1
22	33,5	7,5	ACIn2
23	33,5	0	ACIn3



Tolerance of pinpositions: ±0.5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
D31-D36	Rectifier	1600 V	25 A	Rectifier Diode	
T11-T16	IGBT	1200 V	15 A	Inverter Switch	
D11-D16	FWD	1200 V	15 A	Inverter Diode	
Rt	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 135	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 0 packages see vincotech.com website.

Package data
Package data for *flow* 0 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-FZ12PNA015M7-P840C28-D1-14	26 Nov. 2018		

DISCLAIMER

The information, specifications, procedures, methods and recommendations herein (together "information") are presented by Vincotech to reader in good faith, are believed to be accurate and reliable, but may well be incomplete and/or not applicable to all conditions or situations that may exist or occur. Vincotech reserves the right to make any changes without further notice to any products to improve reliability, function or design. No representation, guarantee or warranty is made to reader as to the accuracy, reliability or completeness of said information or that the application or use of any of the same will avoid hazards, accidents, losses, damages or injury of any kind to persons or property or that the same will not infringe third parties rights or give desired results. It is reader's sole responsibility to test and determine the suitability of the information and the product for reader's intended use.

LIFE SUPPORT POLICY
Vincotech products are not authorised for use as critical components in life support devices or systems without the express written approval of Vincotech.
As used herein:
1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.